

ABSTRACT OF THE DISCLOSURE

A substantially flat heat transferring device and a method of fabricating the same are provided. The device includes a lower plate, an upper plate, a wick plate, and a liquid-phase coolant, while the lower plate contacts a heat source at its bottom. The upper plate is hermetically coupled with the lower plate along its edge to form a void therebetween. The wick plate is provided between the upper plate and the lower plate and is maintained in position relative to the lower plate by surface tension of the liquid-phase coolant. The liquid-phase coolant transfers heat by circulating between a vaporization part, where the heat source is located, to a condensing part. Here, the wick plate includes a plurality of holes and a plurality of planar wicks and makes the liquid-phase coolant flow from the condensing part to the vaporization part by capillary force between itself and the lower plate.